

74ALVCH16244

Low-Voltage 16-Bit Buffer with Bus Hold 1.8/2.5/3.3 V (3-State, Non-Inverting)

The 74ALVCH16244 is an advanced performance, non-inverting 16-bit buffer. It is designed for very high-speed, very low-power operation in 1.8 V, 2.5 V or 3.3 V systems.

The 74ALVCH16244 is nibble controlled with each nibble functioning identically, but independently. The control pins may be tied together to obtain full 16-bit operation. The 3-state outputs are controlled by an Output Enable ($\overline{\text{OEn}}$) input for each nibble. When $\overline{\text{OEn}}$ is LOW, the outputs are on. When $\overline{\text{OEn}}$ is HIGH, the outputs are in the high impedance state. The data inputs include active bushold circuitry, eliminating the need for external pull-up resistors to hold unused or floating inputs at a valid logic state.

- Designed for Low Voltage Operation: $V_{CC} = 1.65 - 3.6 \text{ V}$
- 3.6 V Tolerant Inputs and Outputs
- High Speed Operation: 3.0 ns max for 3.0 to 3.6 V
3.7 ns max for 2.3 to 2.7 V
6.0 ns max for 1.65 to 1.95 V
- Static Drive: $\pm 24 \text{ mA}$ Drive at 3.0 V
 $\pm 12 \text{ mA}$ Drive at 2.3 V
 $\pm 4 \text{ mA}$ Drive at 1.65 V
- Supports Live Insertion and Withdrawal
- Includes Active Bushold to Hold Unused or Floating Inputs at a Valid Logic State
- I_{OFF} Specification Guarantees High Impedance When $V_{CC} = 0 \text{ V}^\dagger$
- Near Zero Static Supply Current in All Three Logic States (40 μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds $\pm 250 \text{ mA}$ @ 125°C
- ESD Performance: Human Body Model >2000V; Machine Model >200V
- Second Source to Industry Standard 74ALVCH16244

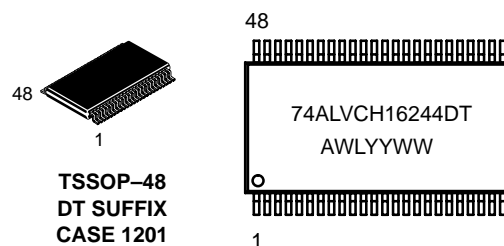
† To ensure the outputs activate in the 3-state condition, the output enable pins should be connected to V_{CC} through a pull-up resistor. The value of the resistor is determined by the current sinking capability of the output connected to the $\overline{\text{OE}}$ pin.



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MARKING DIAGRAM



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
74ALVCH16244DTR	TSSOP	2500/Tape & Reel

74ALVCH16244

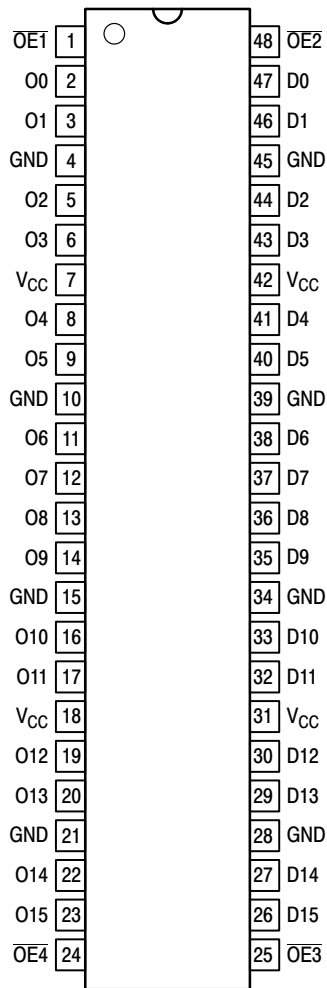


Figure 1. 48-Lead Pinout
(Top View)

PIN NAMES

Pins	Function
OE _n	Output Enable Inputs
D0–D15	Inputs
O0–O15	Outputs

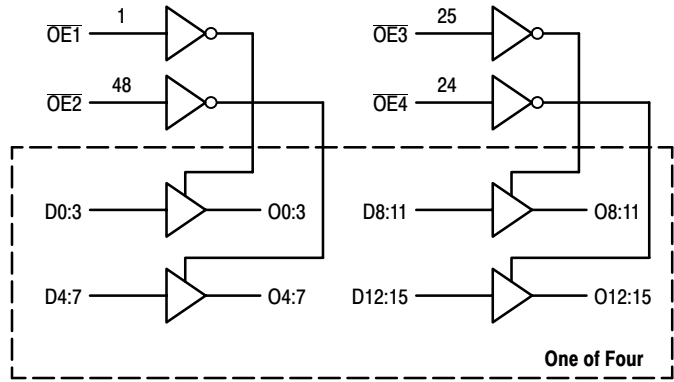


Figure 2. Logic Diagram

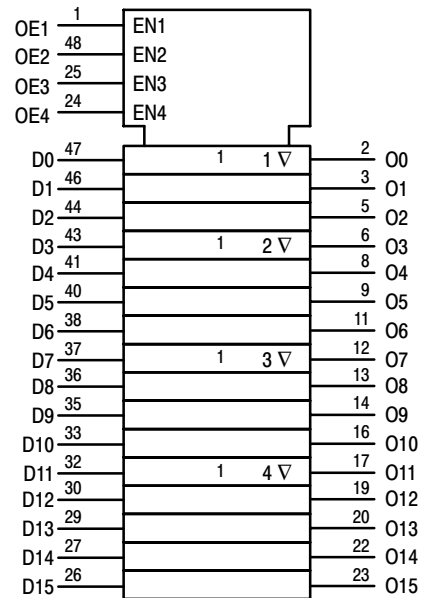


Figure 3. IEC Logic Diagram

OE ₁	D0:3	O0:3	OE ₂	D4:7	O4:7	OE ₃	D8:11	O8:11	OE ₄	D12:15	O12:15
L	L	L	L	L	L	L	L	L	L	L	L
L	H	H	L	H	H	L	H	H	L	H	H
H	X	Z	H	X	Z	H	X	Z	H	X	Z

H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; X = High or Low Voltage Level and Transitions Are Acceptable, for I_{CC} reasons, DO NOT FLOAT Inputs

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MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Value	Unit
V _{CC}	DC Supply Voltage	− 0.5 to + 4.6	V
V _I	DC Input Voltage	− 0.5 to + 4.6	V
V _O	DC Output Voltage	− 0.5 to + 4.6	V
I _{IK}	DC Input Diode Current V _I < GND	− 50	mA
I _{OK}	DC Output Diode Current V _O < GND	− 50	mA
I _O	DC Output Sink Current	± 50	mA
I _{CC}	DC Supply Current per Supply Pin	± 100	mA
I _{GND}	DC Ground Current per Ground Pin	± 100	mA
T _{STG}	Storage Temperature Range	− 65 to + 150	°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds	260	°C
T _J	Junction Temperature Under Bias	+ 150	°C
θ _{JA}	Thermal Resistance (Note 2)	90	°C/W
MSL	Moisture Sensitivity	Level 1	
FR	Flammability Rating Oxygen Index: 30 to 35	UL 94 V-O @ 0.125 in	
V _{ESD}	ESD Withstand Voltage Human Body Model (Note 3) Machine Model (Note 4) Charged Device Model (Note 5)	> 2000 > 200 N/A	V
I _{LATCH-UP}	Latch-Up Performance Above V _{CC} and Below GND at 125°C (Note 6)	± 250	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute maximum-rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

1. I_O absolute maximum rating must be observed.
2. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
3. Tested to EIA/JESD22-A114-A.
4. Tested to EIA/JESD22-A115-A.
5. Tested to JESD22-C101-A.
6. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Supply Voltage Operating Data Retention Only	2.3 1.5	3.6 3.6	V
V _I	Input Voltage (Note 7)	−0.5	3.6	V
V _O	Output Voltage (Active State) (3-State)	0 0	3.6 3.6	V
T _A	Operating Free-Air Temperature	− 40	+ 85	°C
Δt/ΔV	Input Transition Rise or Fall Rate V _{CC} = 2.5 V ± 0.2 V V _{CC} = 3.0 V ± 0.3 V	0 0	20 10	ns/V

7. Unused inputs may not be left open. All inputs must be tied to a high-logic voltage level or a low-logic input voltage level.

DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	T _A = -40°C to +85°C		Unit
			Min	Max	
V _{IH}	HIGH Level Input Voltage (Note 8)	1.65 V ≤ V _{CC} < 2.3 V	0.65 × V _{CC}		V
		2.3 V ≤ V _{CC} ≤ 2.7 V	1.7		
		2.7 V < V _{CC} ≤ 3.6 V	2.0		
V _{IL}	LOW Level Input Voltage (Note 8)	1.65 V ≤ V _{CC} < 2.3 V		0.35 × V _{CC}	V
		2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	
		2.7 V < V _{CC} ≤ 3.6 V		0.8	
V _{OH}	HIGH Level Output Voltage	1.65 V ≤ V _{CC} ≤ 3.6 V; I _{OH} = -100 μA	V _{CC} - 0.2		V
		V _{CC} = 1.65 V; I _{OH} = -4 mA	1.20		
		V _{CC} = 2.3 V; I _{OH} = -6 mA	2.0		
		V _{CC} = 2.3 V; I _{OH} = -12 mA	1.7		
		V _{CC} = 2.7 V; I _{OH} = -12 mA	2.2		
		V _{CC} = 3.0 V; I _{OH} = -12 mA	2.4		
		V _{CC} = 3.0 V; I _{OH} = -24 mA	2.0		
V _{OL}	LOW Level Output Voltage	1.65 V ≤ V _{CC} ≤ 3.6 V; I _{OL} = 100 μA		0.2	V
		V _{CC} = 1.65 V; I _{OL} = 4 mA		0.45	
		V _{CC} = 2.3 V; I _{OL} = 6 mA		0.4	
		V _{CC} = 2.3 V; I _{OL} = 12 mA		0.7	
		V _{CC} = 2.7 V; I _{OL} = 12 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
I _I	Input Leakage Current	1.65 V ≤ V _{CC} ≤ 3.6 V; 0 V ≤ V _I ≤ 3.6 V		± 5.0	μA
I _{I(HOLD)}	Minimum Bus-hold Input Current	V _{CC} = 3.6 V; V _{IN} = 0 to 3.6 V		± 500	μA
		V _{CC} = 3.0 V, V _{IN} = 0.8 V	75		
		V _{CC} = 3.0 V, V _{IN} = 2.0 V	-75		
		V _{CC} = 2.3 V, V _{IN} = 0.7 V	45		
		V _{CC} = 2.3 V, V _{IN} = 1.7 V	-45		
		V _{CC} = 1.65 V, V _{IN} = 0.58 V	25		
		V _{CC} = 1.65 V, V _{IN} = 1.07 V	-25		
I _{OZ}	3-State Output Current	1.65 V ≤ V _{CC} ≤ 3.6 V; 0 V ≤ V _O ≤ 3.6 V; V _I = V _{IH} or V _{IL}		± 10	μA
I _{OFF}	Power-Off Leakage Current	V _{CC} = 0 V; V _I or V _O = 3.6 V		10	μA
I _{CC}	Quiescent Supply Current (Note 9)	1.65 V ≤ V _{CC} ≤ 3.6 V; V _I = GND or V _{CC}		40	μA
		1.65 V ≤ V _{CC} ≤ 3.6 V; 3.6 V ≤ V _I , V _O ≤ 3.6 V		± 40	
ΔI _{CC}	Increase in I _{CC} per Input	2.7 V < V _{CC} ≤ 3.6 V; V _{IH} = V _{CC} - 0.6 V		750	μA

8. These values of V_I are used to test DC electrical characteristics only.

9. Outputs disabled or 3-state only.

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AC CHARACTERISTICS (Note 10; $t_R = t_F = 2.0$ ns; $C_L = 30$ pF; $R_L = 500 \Omega$)

Symbol	Parameter	Waveform	Limits						Unit
			T _A = −40°C to +85°C						
			V _{CC} = 3.0 V to 3.6 V		V _{CC} = 2.3 V to 2.7 V		V _{CC} = 1.65 V – 1.95 V		
			Min	Max	Min	Max	Min	Max	
t _{PLH}	Propagation Delay	1	1.0	3.0	1.0	3.7	1.0	6.0	ns
t _{PHL}	Input to Output		1.0	3.0	1.0	3.7	1.0	6.0	
t _{PZH}	Output Enable Time to High	2	1.0	4.4	1.0	5.7	1.0	8.2	ns
t _{PZL}	Output Enable Time to Low		1.0	4.4	1.0	5.7	1.0	8.2	
t _{PHZ}	Output Disable Time From High	2	1.0	4.1	1.0	5.2	1.0	6.8	ns
t _{PLZ}	Output Disable Time From Low		1.0	4.1	1.0	5.2	1.0	6.8	
t _{OSHL}	Output-to-Output Skew			0.5		0.5		0.75	ns
t _{OSLH}	(Note 11)			0.5		0.5		0.75	

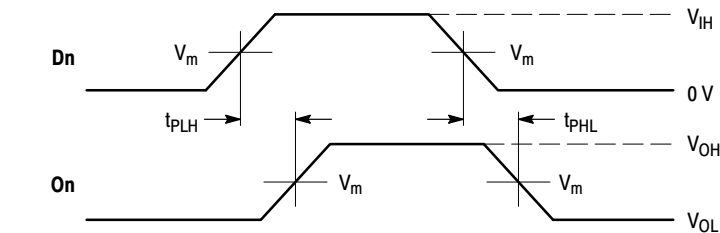
10. For $C_L = 50$ pF, add approximately 300 ps to the AC maximum specification.

11. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

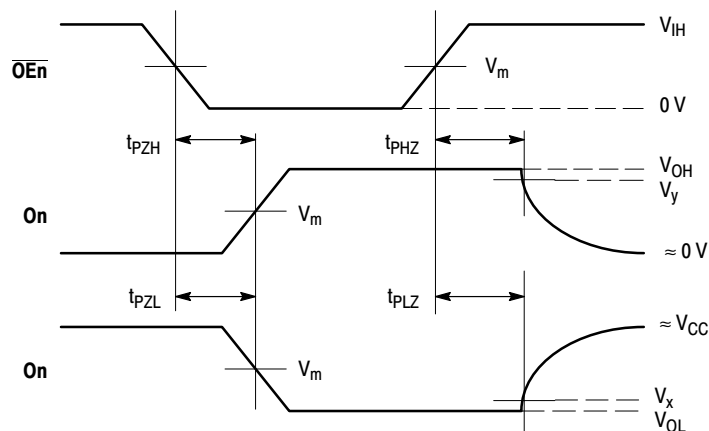
Symbol	Parameter	Condition	Typical	Unit
C_{IN}	Input Capacitance	Note 12	6	pF
C_{OUT}	Output Capacitance	Note 12	7	pF
C_{PD}	Power Dissipation Capacitance	Note 12, 10 MHz	20	pF

12. $V_{CC} = 1.8, 2.5$ or 3.3 V; $V_I = 0$ V or V_{CC} .



WAVEFORM 1 - PROPAGATION DELAYS

$t_R = t_F = 2.0$ ns, 10% to 90%; $f = 1$ MHz; $t_W = 500$ ns



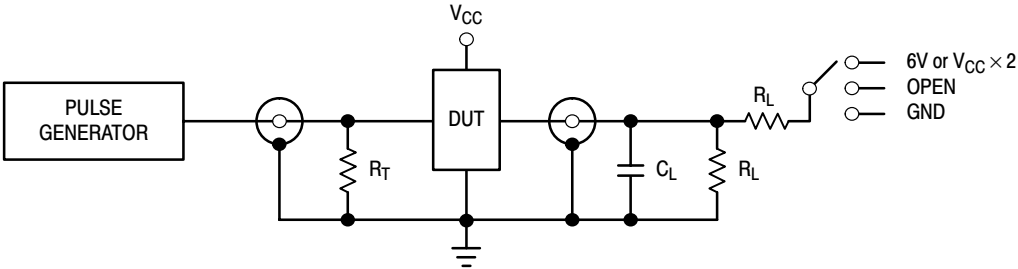
WAVEFORM 2 - OUTPUT ENABLE AND DISABLE TIMES

$t_R = t_F = 2.0$ ns, 10% to 90%; $f = 1$ MHz; $t_W = 500$ ns

Figure 4. AC Waveforms

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Symbol	V _{CC}		
	3.3 V ±0.3 V	2.5 V ±0.2 V	1.8 V ±0.15 V
V _{IH}	2.7 V	V _{CC}	V _{CC}
V _m	1.5 V	V _{CC} /2	V _{CC} /2
V _x	V _{OL} + 0.3 V	V _{OL} + 0.15 V	V _{OL} + 0.15 V
V _y	V _{OH} - 0.3 V	V _{OH} - 0.15 V	V _{OH} - 0.15 V



TEST	SWITCH
t_{PLH} , t_{PHL}	Open
t_{PZL} , t_{PLZ}	6 V at $V_{CC} = 3.3 \pm 0.3$ V; $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2$ V; 1.8 ± 0.15 V
t_{PZH} , t_{PHZ}	GND

$C_L = 50$ pF for $V_{CC} = 3.0 \pm 0.3$ V
 $R_L = 500 \Omega$ or equivalent
 $R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 5. Test Circuit

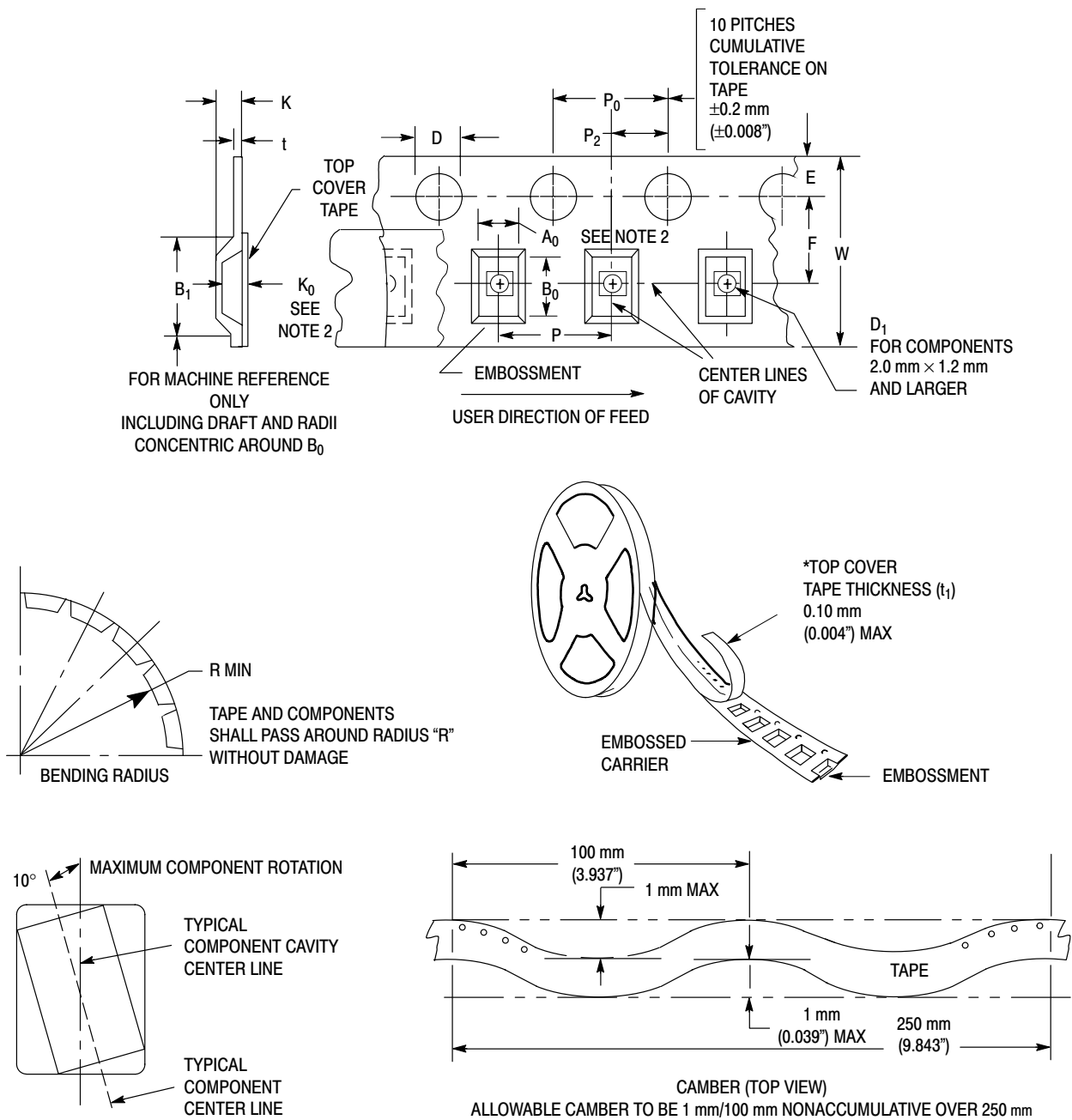


Figure 6. Carrier Tape Specifications

EMBOSSED CARRIER DIMENSIONS (See Notes 13 and 14)

Tape Size	B_1 Max	D	D_1	E	F	K	P	P_0	P_2	R	T	W
24mm	20.1mm (0.791")	1.5 + 0.1mm - 0.0 (0.059 + 0.004" - 0.0)	1.5mm Min (0.060")	1.75 \pm 0.1 mm (0.069 \pm 0.004")	11.5 \pm 0.10 mm (0.453 \pm 0.004")	11.9 mm Max (0.468")	16.0 \pm 0.1 mm (0.63 \pm 0.004")	4.0 \pm 0.1 mm (0.157 \pm 0.004")	2.0 \pm 0.1 mm (0.079 \pm 0.004")	30 mm (1.18")	0.6 mm (0.024")	24.3 mm (0.957")

13. Metric Dimensions Govern—English are in parentheses for reference only.

14. A_0 , B_0 , and K_0 are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity.

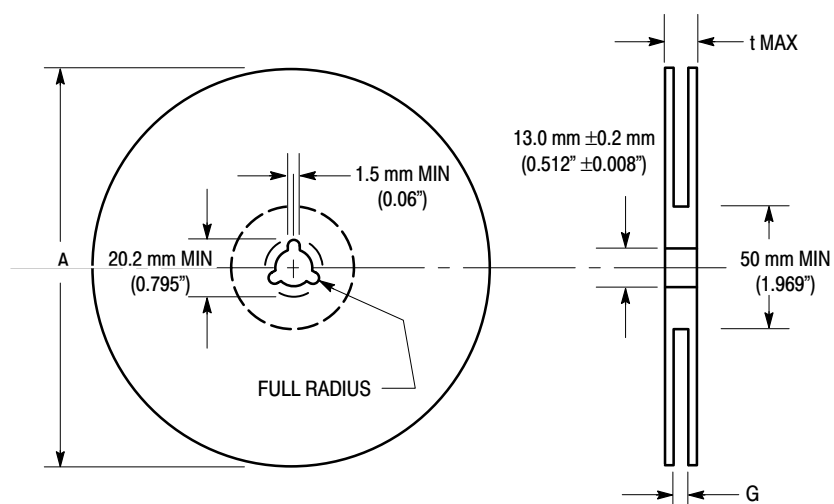


Figure 7. Reel Dimensions

REEL DIMENSIONS

Tape Size	A Max	G	t Max
24 mm	360 mm (14.173")	24.4 mm + 2.0 mm, -0.0 (0.961" + 0.078", -0.00)	30.4 mm (1.197")

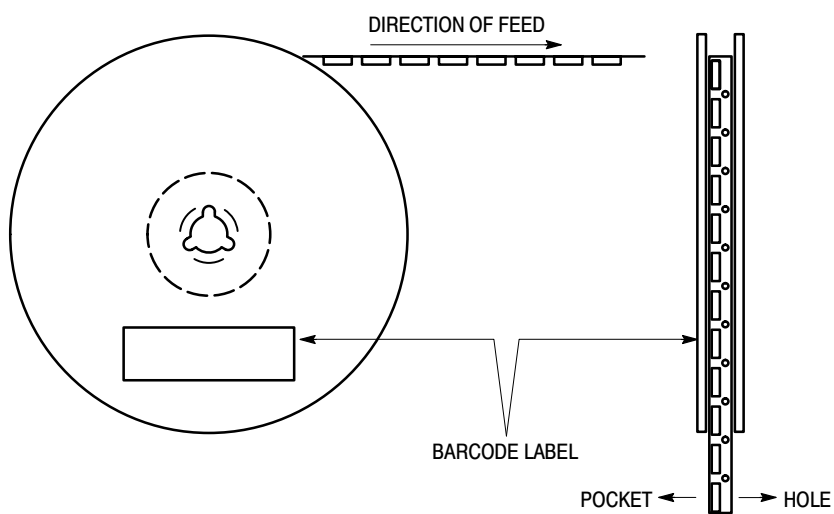


Figure 8. Reel Winding Direction

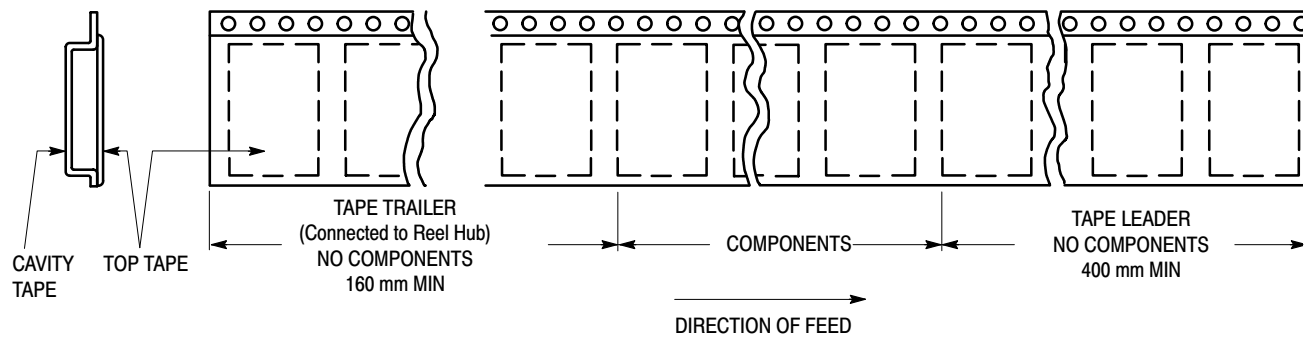


Figure 9. Tape Ends for Finished Goods

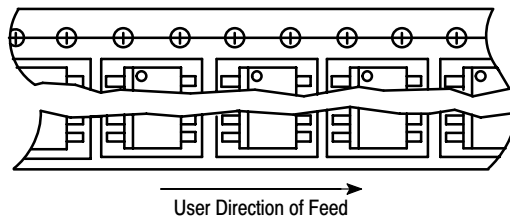


Figure 10. Reel Configuration

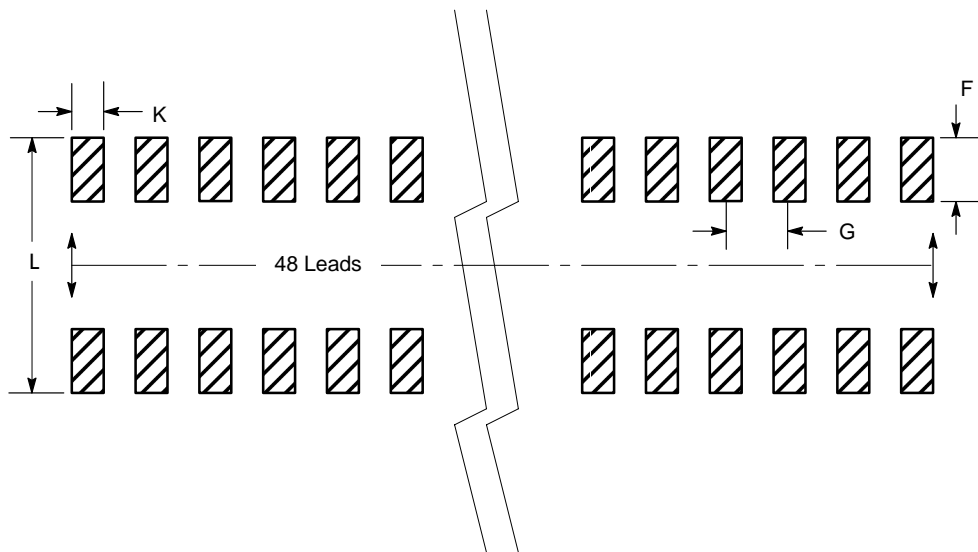



Figure 11. Package Footprint

Notes

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